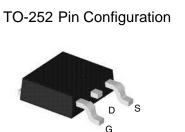
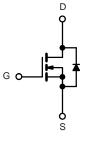
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>			
60	0.0049 at V <sub>GS</sub> = 10 V	60			

**Din-Tek** 

SEMICONDUCTOR



Top View



N-Channel MOSFET

#### FEATURES

- 175 °C Junction Temperature
- DT-Trench Power MOSFET
- 100 %  $R_g$  and UIS Tested

## Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Industrial and Motor Drive applications

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Drain Current (T 175 °C)b	T <sub>C</sub> = 25 °C	1-	60			
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	50 <sup>a</sup>			
Pulsed Drain Current	I <sub>DM</sub>	210	A			
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	60 <sup>a</sup>				
Avalanche Current	I <sub>AS</sub>	62				
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ		
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	146	w		
	T <sub>A</sub> = 25 °C	' D	12 <sup>b,c</sup>			
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	$t \le 10 \text{ sec}$	R <sub>thJA</sub>	13	20		
Maximum Junction-to-Ambient*	Steady State		35	50	°C/W	
Maximum Junction-to-Case		R <sub>thJC</sub>	0.76	1.0		

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c.  $t \leq 10$  s.





# DTU3203

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<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions Min		Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$\begin{tabular}{ c c c c c } \hline V_{GS} = 0 \ V, \ I_D = 250 \ \mu A & 60 \\ \hline V_{DS} = V_{GS}, \ I_D = 250 \ \mu A & 1 \\ \hline \end{tabular}$				V	
Gate Threshold Voltage	V <sub>GS(th)</sub>			-	3		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 48 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$			50	μA	
		$V_{DS} = 48 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	65			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		0.0049	0.0059	Ω	
	Б	$V_{GS}$ = 10 V, $I_{D}$ = 10 A, $T_{J}$ = 125 °C		0.0055	0.0068		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS}$ = 10 V, $I_{D}$ = 10 A, $T_{J}$ = 175 °C		0.0063	0.0079		
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		0.0058	0.0075		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		80		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			10620			
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, f = 1 MHz		750		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			85			
Total Gate Charge <sup>c</sup>	Qg			58	75		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		15		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			19			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			23			
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 48 V, $R_L$ = 0.6 $\Omega$		32		~~~	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D} \cong$ 10 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 2.5 $\Omega$		28		ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	1		11			
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)		-			
Pulsed Current	I <sub>SM</sub>				210	А	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		1		V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 10 A, di/dt = 100 A/µs		31		ns	

Notes:

a. For design aid only; not subject to production testing.

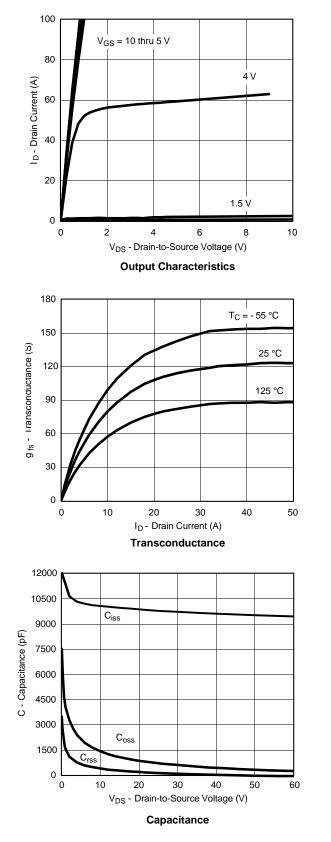
b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

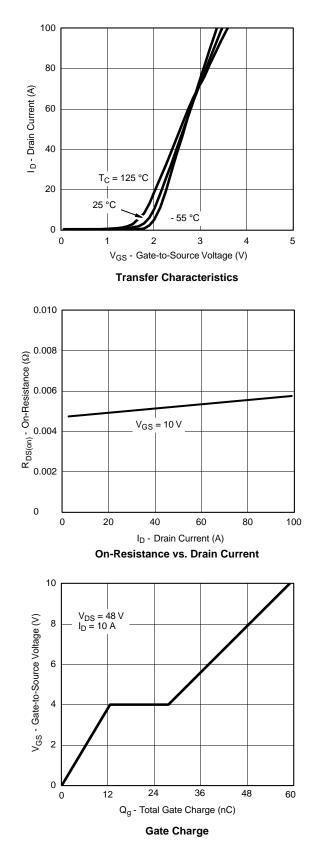
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



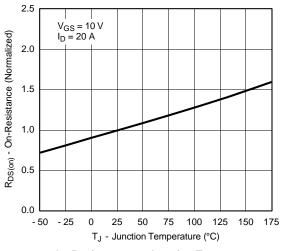
### TYPICAL CHARACTERISTICS (25 °C unless noted)



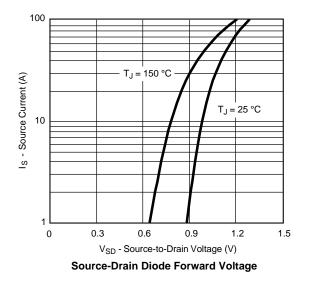




## TYPICAL CHARACTERISTICS (25 °C unless noted)

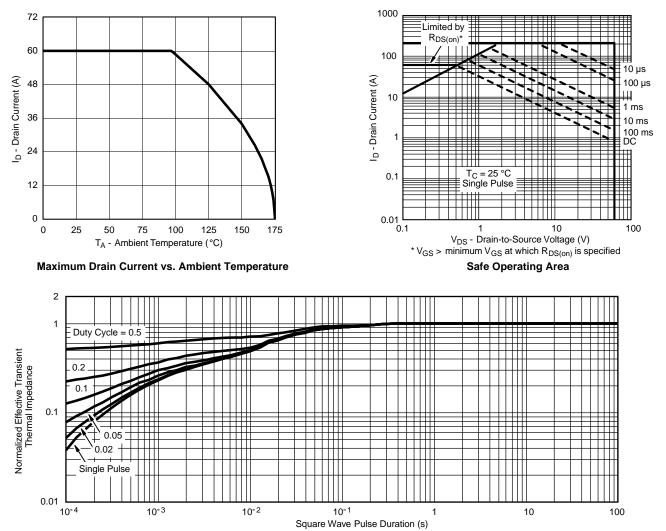


**On-Resistance vs. Junction Temperature** 





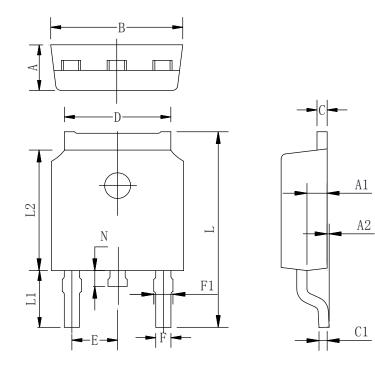
#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



# TO-252-2L PACKAGE OUTLINE



## COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max		
A	2.10	2.30	2.50		
A1	0.88	1.01	1.16		
A2	0.00	0.15	0.28		
В	6.40	6.60	6.80		
С	0.42	0.50	0.63		
C1	0.42	0.50	0.63		
D	5.08	5.32	5.65		
Е	2.286 TYP				
F	0.63	0.76	0.89		
F1	0.64	0.86	1.08		
L	9.30	9.90	10.80		
L1	2.4	2.8	3.6		
L2	5.90	6.10	6.55		
N	0.57	0.80	1.05		

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